FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention

Method of Managing Wafer Defects

Application Number:

Date:

First Named Applicant: Hung-En Tai
Attorney Docket Number: LKSP0051USA

TOTAL FEE AUTHORIZED \$810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$				
Utility Filing Fee	1001	770	770				
Subtotal For Basic Filing Fees: \$ 770							

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$		
Total Claims: 7	0	1202	18	0		
Independent Claims : 1	0	1201	86	0		
Subtotal For Extra Claims Fees: \$ (

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$		
Recording Each Patent	00000000	1	8021	40	40		
Assignment Per Property Fee							
Subtotal For Additional Fees: \$40							

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 503105

Access Code ****

Deposit name: North America Intellectual Property Corporation

Deposit authorized name: /WINSTON HSU/

Signature: /VAEB-JMXX-8IIL/

Date (YYYYMMDD): 2004-09-08

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.